

## Features

- Super low gate charge
- Green device available
- Excellent  $C_{dv}$  /  $d_i$  effect decline
- Advanced high cell density trench technology
- Halogen free
- Qualified to AEC-Q101 standards for high reliability

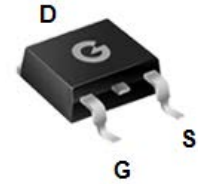
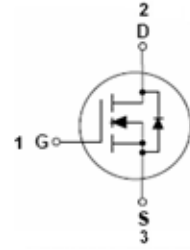
HF

## Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

## Mechanical Data

- Case: TO-252
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



TO-252

## Ordering Information

| Part Number | Package | Shipping Quantity                     | Marking Code |
|-------------|---------|---------------------------------------|--------------|
| TBL450N15D  | TO-252  | 80pcs / Tube or 2500pcs / Tape & Reel | 450N15D      |

## Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

| Parameter                                                                                 | Symbol   | Value    | Unit |
|-------------------------------------------------------------------------------------------|----------|----------|------|
| Drain-to-Source Voltage                                                                   | $V_{DS}$ | 150      | V    |
| Gate-to-Source Voltage                                                                    | $V_{GS}$ | $\pm 20$ | V    |
| Continuous Drain Current ( $T_C = 25^\circ\text{C}, V_{GS} = 10\text{V}$ ) <sup>*1</sup>  | $I_D$    | 30       | A    |
| Continuous Drain Current ( $T_C = 100^\circ\text{C}, V_{GS} = 10\text{V}$ ) <sup>*1</sup> |          | 22       | A    |
| Pulsed Drain Current <sup>*2</sup>                                                        | $I_{DM}$ | 60       | A    |
| Single Pulse Avalanche Energy <sup>*3</sup>                                               | $E_{AS}$ | 216      | mJ   |

## Thermal Characteristics

| Parameter                                         | Symbol          | Value           | Unit               |
|---------------------------------------------------|-----------------|-----------------|--------------------|
| Power Dissipation ( $T_C = 25^\circ\text{C}$ )    | $P_D$           | 115             | W                  |
| Thermal Resistance Junction-to-Case <sup>*1</sup> | $R_{\theta JC}$ | 1.09            | $^\circ\text{C/W}$ |
| Operating Junction Temperature Range              | $T_J$           | $-55 \sim +150$ | $^\circ\text{C}$   |
| Storage Temperature Range                         | $T_{STG}$       | $-55 \sim +150$ | $^\circ\text{C}$   |

### Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

| Symbol                             | Parameter                                       | Test Condition                                                                                   | Min. | Typ. | Max. | Unit |
|------------------------------------|-------------------------------------------------|--------------------------------------------------------------------------------------------------|------|------|------|------|
| Static Characteristics             |                                                 |                                                                                                  |      |      |      |      |
| V <sub>DSS</sub>                   | Drain-Source Breakdown Voltage                  | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA                                                     | 150  | -    | -    | V    |
| I <sub>DSS</sub>                   | Zero Gate Voltage Drain Current                 | V <sub>DS</sub> = 120V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 25°C                              | -    | -    | 1    | μA   |
|                                    |                                                 | V <sub>DS</sub> = 120V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 55°C                              | -    | -    | 5    | μA   |
| I <sub>GSS</sub>                   | Gate-Body Leakage Current                       | V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V                                                     | -    | -    | ±100 | nA   |
| On Characteristics                 |                                                 |                                                                                                  |      |      |      |      |
| R <sub>DS(ON)</sub>                | Static Drain-Source On-resistance <sup>*2</sup> | V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A                                                      | -    | -    | 46   | mΩ   |
|                                    |                                                 | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A                                                     | -    | -    | 50   | mΩ   |
| V <sub>GS(th)</sub>                | Gate Threshold Voltage                          | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA                                       | 1.2  | -    | 2.5  | V    |
| Dynamic Characteristics            |                                                 |                                                                                                  |      |      |      |      |
| C <sub>ISS</sub>                   | Input Capacitance                               | V <sub>GS</sub> = 0V<br>V <sub>DS</sub> = 25V<br>f = 1.0MHz                                      | -    | 3755 | -    | pF   |
| C <sub>OSS</sub>                   | Output Capacitance                              |                                                                                                  | -    | 207  | -    |      |
| C <sub>RSS</sub>                   | Reverse Transfer Capacitance                    |                                                                                                  | -    | 160  | -    |      |
| Switching Characteristics          |                                                 |                                                                                                  |      |      |      |      |
| t <sub>d(ON)</sub>                 | Turn-on Delay Time                              | V <sub>DD</sub> = 50V<br>V <sub>GS</sub> = 4.5V<br>R <sub>G</sub> = 3.3Ω<br>I <sub>D</sub> = 10A | -    | 18   | -    | ns   |
| t <sub>r</sub>                     | Turn-on Rise Time                               |                                                                                                  | -    | 20   | -    |      |
| t <sub>d(OFF)</sub>                | Turn-Off Delay Time                             |                                                                                                  | -    | 65   | -    |      |
| t <sub>f</sub>                     | Turn-Off Fall Time                              |                                                                                                  | -    | 15   | -    |      |
| Q <sub>G</sub>                     | Total Gate-Charge                               | V <sub>DD</sub> = 75V<br>V <sub>GS</sub> = 4.5V<br>I <sub>D</sub> = 10A                          | -    | 40   | -    | nC   |
| Q <sub>GS</sub>                    | Gate to Source Charge                           |                                                                                                  | -    | 10   | -    |      |
| Q <sub>GD</sub>                    | Gate to Drain (Miller) Charge                   |                                                                                                  | -    | 21   | -    |      |
| Source-Drain Diode Characteristics |                                                 |                                                                                                  |      |      |      |      |
| V <sub>SD</sub>                    | Diode Forward Voltage <sup>*2</sup>             | I <sub>SD</sub> = 18A, V <sub>GS</sub> = 0V, T <sub>J</sub> = 25°C                               | -    | -    | 1.2  | V    |
| I <sub>S</sub>                     | Diode Continuous Forward Current <sup>*1</sup>  |                                                                                                  | -    | -    | 30   | A    |

Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L = 0.5\text{mH}$

Ratings and Characteristics Curves (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

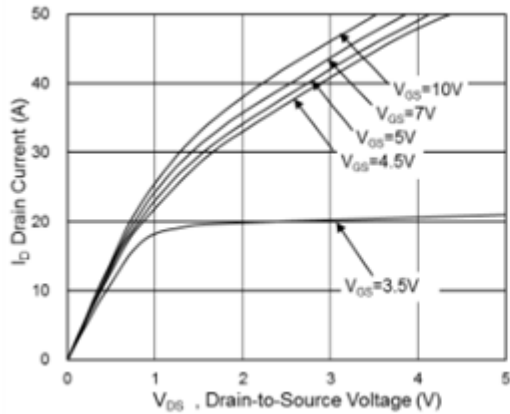


Fig 1 Typical Output Characteristics

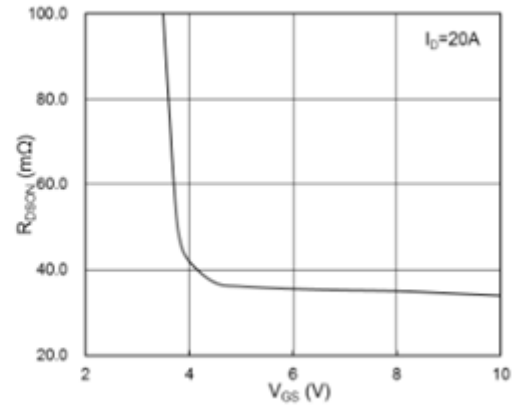


Fig 2 On-Resistance vs. Gate-Source

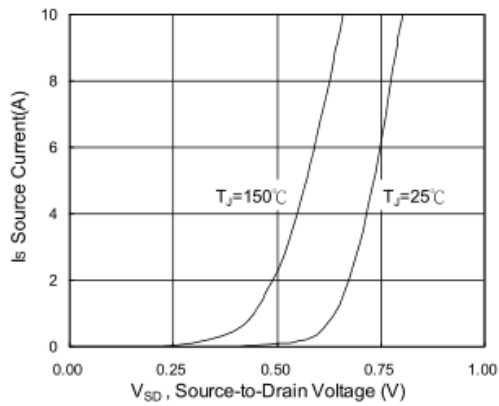


Fig 3 Forward Characteristics Of Reverse diode

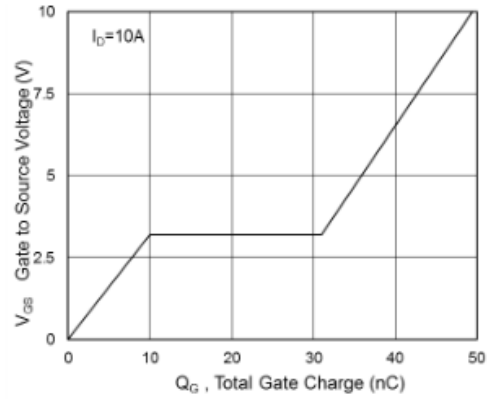


Fig 4 Gate-Charge Characteristics

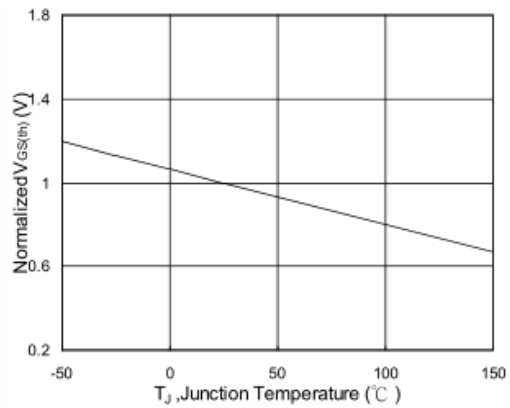


Fig 5 Normalized  $V_{GS(th)}$  vs.  $T_J$

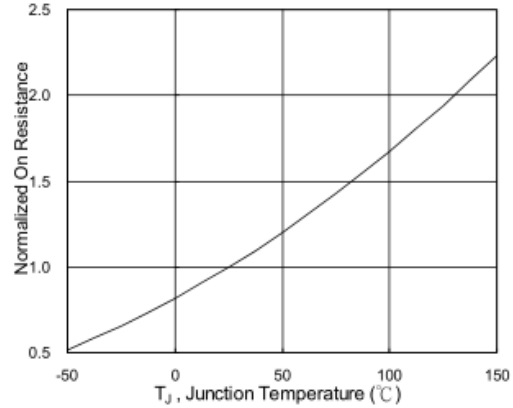


Fig 6 Normalized  $R_{DS(on)}$  vs.  $T_J$

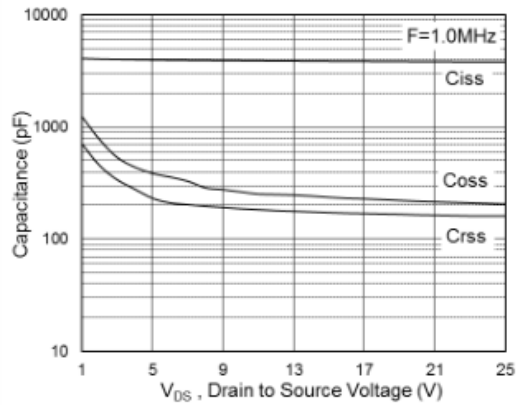


Fig 7 Capacitance

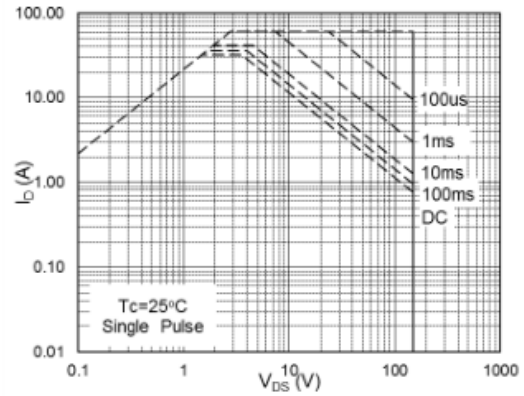


Fig 8 Safe Operating Area

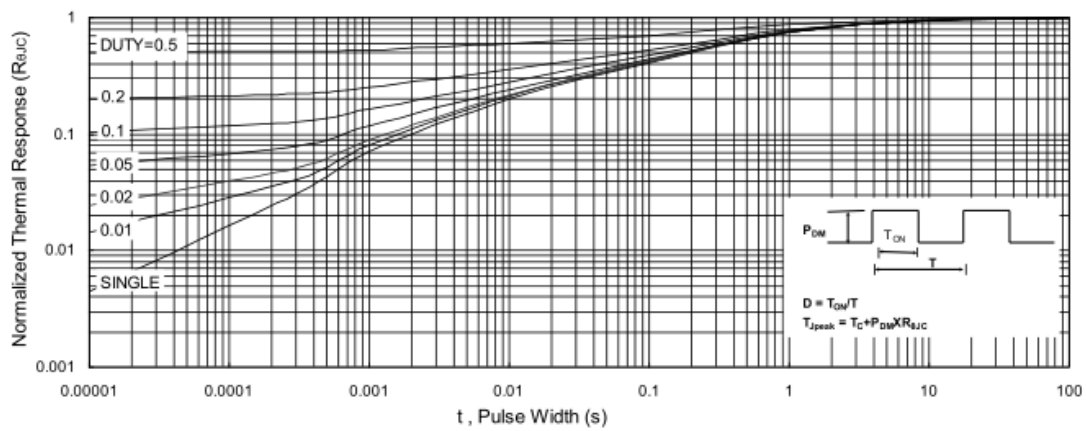
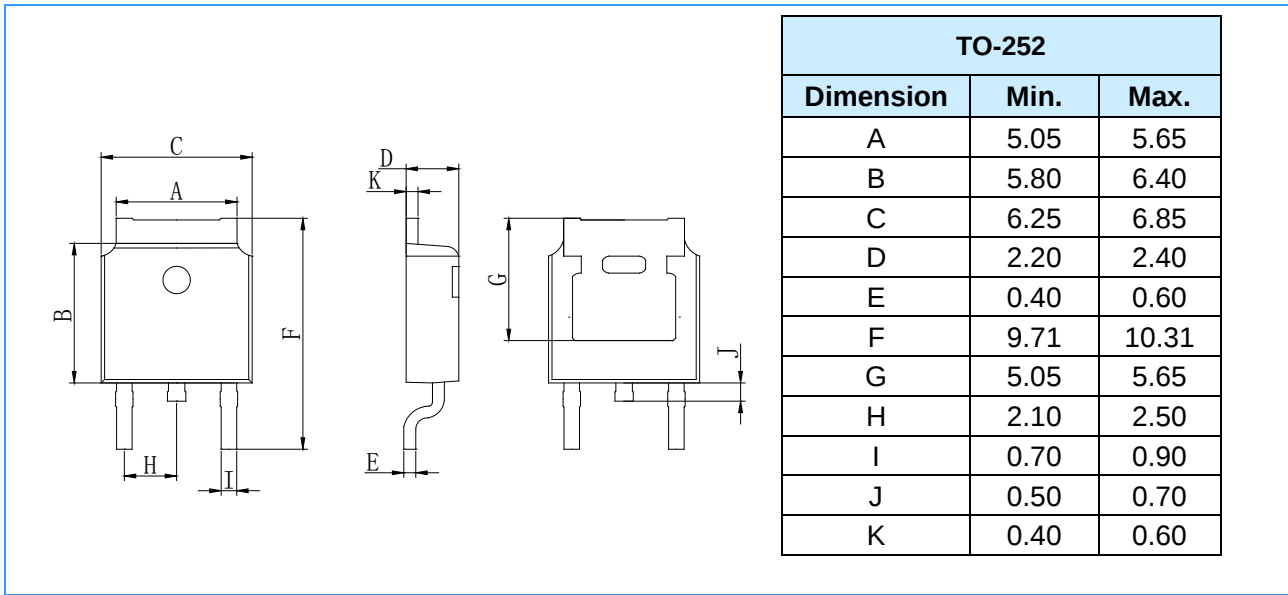
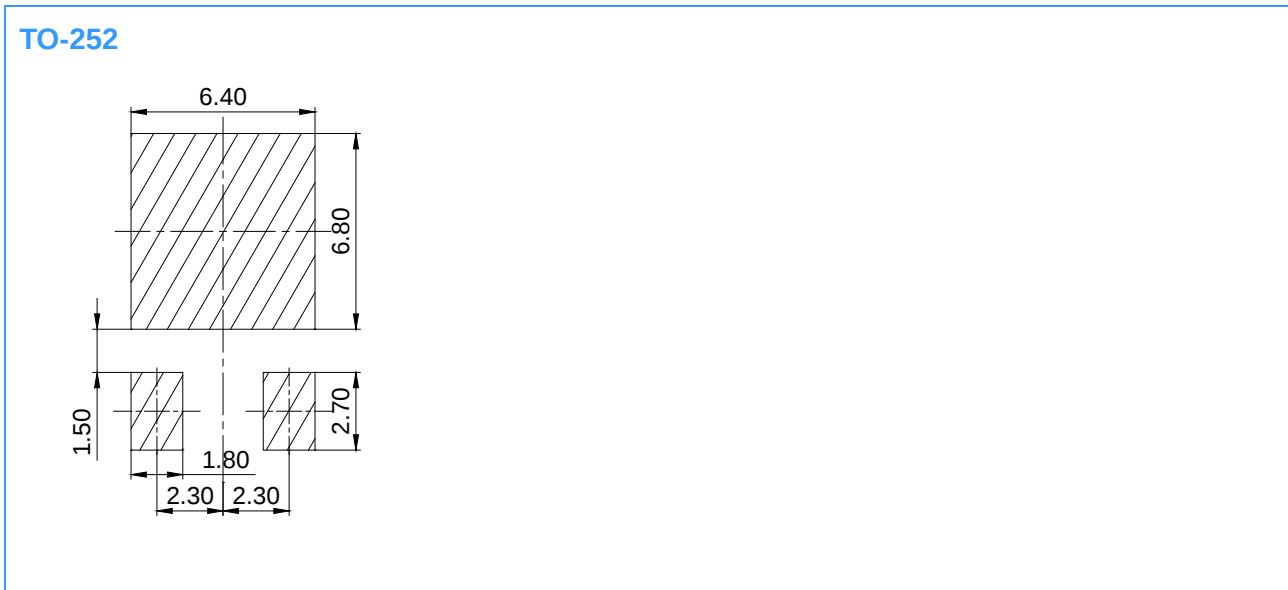


Fig9 Normalized Maximum Transient Thermal Impedance

## Package Outline Dimensions (Unit: mm)



## Mounting Pad Layout (Unit: mm)



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